



## Material Content Data Sheet



<b>Sales Product Name</b>		IFX20001MB V33		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000633418						
<b>Package</b>		PG-SCT595-5-1		<b>Weight*</b>		13.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.294	2.12	2.12	21171	21171
leadframe	inorganic material	silicon	7440-21-3	0.001	0.01		87	
	non noble metal	titanium	7440-32-6	0.006	0.04		436	
	non noble metal	chromium	7440-47-3	0.018	0.13		1308	
	non noble metal	copper	7440-50-8	6.019	43.39	43.57	434049	435880
wire	noble metal	gold	7440-57-5	0.030	0.22	0.22	2152	2152
encapsulation	organic material	carbon black	1333-86-4	0.055	0.40		3984	
	plastics	brominated resin	-	0.069	0.50		4979	
	inorganic material	antimonytrioxide	1309-64-4	0.138	1.00		9959	
	plastics	epoxy resin	-	1.257	9.06		90625	
	inorganic material	silicondioxide	60676-86-0	5.386	38.84	49.80	388394	497941
leadfinish	non noble metal	tin	7440-31-5	0.335	2.42	2.42	24189	24189
plating	noble metal	silver	7440-22-4	0.142	1.02	1.02	10205	10205
glue	plastics	epoxy resin	-	0.021	0.15		1481	
	noble metal	silver	7440-22-4	0.097	0.70	0.85	6981	8462
*deviation	< 10%					Sum in total:	100.00	1000000

### Important Remarks:

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